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(54) **WAFER INSPECTING EQUIPMENT**

by the CCD camera 22.

(57) Abstract:

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PROBLEM TO BE SOLVED: To easily select a desired wafer only and execute defect inspection, by installing a means discriminating a specimen number before a semiconductor wafer reaches an inspecting part, and a selecting means which selects a desired semiconductor wafer on the basis of the number and carries the wafer to the inspecting part.

SOLUTION: A specimen number (wafer number) of a semiconductor wafer (wafer) 10 as the object to be inspected is printed in the peripheral part of a surface where a pattern is not formed. An inspecting part 17 for executing wafer foreign matter inspection is equipped with the following; an inspecting stage 18 for executing foreign matter inspection by mounting the wafer 10, an optical system part 19 for executing the foreign matter inspection, and a stage driving mechanism 20 for moving the inspecting stage 18. A discriminating part 21 of the wafer number of the wafer 10 is installed in the upper part of a prealigner 16, and equipped with a CCD camera 22 as an image reading mechanism for reading the wafer number as an image, and a recognizing part 23 for recognizing the wafer number from the picture image read

